

Bonder

# BS-04

ACF Equipment Partner

# OHASHI

OHASHI Engineering. Co., Ltd.



### Compared to the old BS-02:

- 9.1% smaller footprint
- Compact head design
- Better ergonomics

### Process

## Bonding (Pulsed)

Multiple-head pulsed heat bonder

### Equipment Overview

The BS-04 is a semiautomatic pulsed heat bonder with multiple heads (2-4). Each head is independently controlled and bonds a single ACF site on the array of substrates loaded within the carrier.

Equipment dimension	W x D x H
	800 x 1000 x 2080 (mm)
Weight	~ 700 Kg

Number of operators  
1 person

### Productivity

Varies greatly depending on # of heads. TYP 2.5-3.0 seconds.  
Speak with your supplier for more information

### Highly-Efficient Multiple Head System

One row of assemblies in the carrier is bonded during each cycle, allowing high throughput.

### Toolless Head Changeover

The bonding heads can be changed without using tools, making for faster product changeover times.

### Common Carrier System

The carrier used by the BS-03 is the same common carrier used by the LS-02, MS-04, BS-04, and other units in Ohashi's semiautomatic line of equipment.

### Pulsed Heat

The BS-04 is a pulsed-heat system with a unique ceramic head for durability and excellent flatness & thermal characteristics.

### Safety

This equipment is CE certified.

### Spec. overview

Carrier Size (W)250 x (D)400mm

Tool Size Max. (W)20 x (D)20mm

Utilities Compressed air 0.5Mpa  
Internal vacuum source  
3 Φ 200-220V 50/60Hz 2KVA

# of Bond Heads 2-4 heads

Bond Tolerance TYP ±10um

Interposer Feed Auto-winding

### Manufacturer



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### Distributor



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